

## LHCb Detector Upgrade

曾 鸣 (清华大学) 代表 LHCb中国组

第四届中国LHC物理工作会议 <sup>华中师范大学 2018.12.22</sup>











### LHCb 主要科学目标与探测器





- ・ 理解正反物质不对称: CP破坏
- ・ 间接发现新物理:稀有衰变
- 理解强相互作用机制:强子性质,新强子态
- 其它: 电弱物理, 重离子物理, ...

### LHCb Run 2



LHCb proved itself to be the Forward **General–Purpose Detector at the LHC** 

4

6

- ➢ 运行亮度达到4 × 10<sup>32</sup> cm<sup>-2</sup>s<sup>-1</sup>, 两倍于设计指标
- ➤ 积分亮度超过9fb<sup>-1</sup>



### LHCb Upgrade Motivation



LHCb Upgrade I, with installing in 2019-2020 (LHC LS2) and first

data-taking in Run 3 (2021-2023).

- $\clubsuit$  Goal: increase statistics by more than imes10
- \* Raise operational luminosity by factor of five to  $2 \times 10^{33}$  cm<sup>-2</sup>s<sup>-1</sup>
- Triggerless 40MHz readout (Full software trigger)
- Necessitates redesign of several sub-detectors and overhaul of readout (40MHz readout rate)
- Replace tracking detectors (finer granularity to cope with

higher particle density)

Present L0 hardware trigger (max rate 1 MHz) saturates at high luminosity for hadronic final state modes

### LHCb Upgrade I



All sub-detectors read out at 40 MHz for a fully software trigger.

### LHCb Upgrade I: Tracking - VELO

Current VELO: 21 layers of silicon micro-strips  $\rightarrow$  170 k readout channels Inside LHC vacuum chamber  $\rightarrow$  active area at 8.2 mm from beam  $\rightarrow$  separated from beam only by a 300 µm thin aluminium foil



VELO Upgrade: 26 layers of silicon pixel detectors  $\rightarrow$  41 million readout channels Even closer to beam  $\rightarrow$  active area 8.2  $\rightarrow$  5.1 mm Even less material  $\rightarrow$  thinner sensors (300  $\rightarrow$  200 µm)  $\rightarrow$  thinner aluminum foil (300  $\rightarrow$  250 µm)



### LHCb Upgrade I: Tracking - UT

Current: TT 4 layers of silicon micro-strips  $\rightarrow$  183 µm pitch  $\rightarrow$  40, 30, 20, 10 cm in length  $\rightarrow$  143 k readout channels

Upgrade: UT 4 layers of silicon micro-strips, but finer granularity → 190 and 95 µm pitch → 10 and 5 cm in length → 537 k readout channels and better radiation hardness New readout chip, compatible with 40 MHz readout scheme





### LHCb Upgrade I: Tracking - SciFi

Current: IT & OT3 stations with 4 layers each $\rightarrow$  silicon micro-strips in innermost region $\rightarrow$  straw drift tubes in outer region $\rightarrow$  130 k + 54 k readout channels







### LHCb Upgrade I: Tracking - SciFi

Current: IT & OT3 stations with 4 layers each $\rightarrow$  silicon micro-strips in innermost region $\rightarrow$  straw drift tubes in outer region $\rightarrow$  130 k + 54 k readout channels



#### Upgrade: SciFi 3 stations of scintillating fibres $\rightarrow$ 2.5 m long, 250 µm diameter $\rightarrow$ read out with silicon photomultipliers $\rightarrow$ 590 k readout channels



#### 2018/12/22

### LHCb Upgrade I: PID Detector – RICH, Muon, Calorimeters

#### **RICH:**

- New photo-detectors and readout chain.
- 6x6 and 2.9x2.9 mm2 pixels multi-anode photomultipliers (MaPMTs).
- Modified optics and mechanics to reduce RICH1 occupancy.

#### **Calorimeters:**

- Electromagnetic (ECAL) and hadronic (HCAL) calorimeters remain identical
- New readout electronics.
- ECAL inner modules replaced in LS3.

#### **Muon Stations:**

• New readout electronics and increased granularity.





RICH module equipped with MaPMTs

11

### LHCb Upgrade I: Trigger

#### LHC Run II (2015)



Upgrade

### LHCb Upgrade II



LHCb Upgrade II, with installing in 2030 (LHC LS4).

✤ Raise operational luminosity by another factor of ten to 1.5-2×10<sup>34</sup> cm<sup>-2</sup>s<sup>-1</sup>

- Detectors with even finer granularity and with excellent timing resolution (4D resolution)
- Radiation hardness !

### LHCb Upgrade II

Examples of detector developments VELO: silicon pixels with timing resolution  $\rightarrow$  LGAD (Limited Gain Avalanche Detectors) Tracking: central region with silicon  $\rightarrow$  HV-MAPS (Monolithic Pixels) Muon detectors: finer granularity  $\rightarrow \mu$ -RWELL









## LHCb Upgrade I: SciFi

### LHCb Upgrade I: SciFi

Goal: increase statistics by more than ×10
 ✓ Operate at 2×10<sup>33</sup>cm<sup>-2</sup>s<sup>-1</sup> → 50 fb<sup>-1</sup>
 ✓ Triggerless 40MHz readout

Scintillating Fibre (Sci-Fi) Tracker
 ✓ Fast, high efficiency (~99%)
 ✓ High granularity (250µm)
 ✓ High resolution (<100µm)</li>
 ✓ Low mass (<1% X<sub>0</sub>/layer)
 ✓ Radiation hardness (up to 35kGy)



Schematic view of the current LHCb detector

### SciFi – Fibre Mat & Module

- 250µm diameter scintillating fibre wound into a 6-layer 2.4m-long fibre mat
  - $\checkmark$  one end equipped with a mirror
  - ✓ read out by  $4 \times \text{SiPM}$  arrays
- 8 × fibre mat + honeycomb = sandwich-structure 0.5m × 5m module



### Sci-Fi readout electronics (FE)

Tracker structure:

- ✓ 3 Tracking Stations
  - ✓ 12 detector layers (X-U-V-X, 5°)
    - ✓ 144 modules

✤Electronics design:

- ✓ ~340m<sup>2</sup> total active surface
- ✓ 590,000 SiPM channels
- ✓ 12,000 PACIFIC chips needed
- ✓ 2,500 Frontend Electronic Boards

#### ✤LHCb China Group 2016~2018:

- ✓ Co-design Sci-Fi Frontend Electronic Boards
- ✓ Manufacturing all Frontend Boards in China, testing a part
- ✓ Sci-Fi Readout Electronics Quality Assurance System (For chips and boards)
- ✓ Readout Electronics for Detector Performance Evaluation (>20 setups in Sci-Fi group<sup>4</sup>)<sup>sn</sup>

mirror





### PACIFIC5



### **PACIFIC Carrier Board**

We decided to re-optimize the routing of the PACIFIC Carrier Board

- →  $4 \times \text{PACIFIC ASICs}$  (196-pin BGA packaged)
- ✓ 4 × temperature measurement circuits (voltage divider circuits with NTC, 2 for SiPMs, 2 for the ASICs)
- > 4  $\times$  SiPM bias voltage measurement circuits (voltage divider circuits)
- 1 × BoardID IC (DS2401 64-bit unique, factory-lasered silicon serial number, no permanent damage up to 140Gy)

http://radwg.web.cern.ch/RadWG/Pages/showExternal.aspx?GotoUrl=https://twiki.cern.ch/twiki/bin/viewauth/Main/Tullios
<u>PreferredPartList</u>

- $4 \times \text{SiPM}$  flex cable connectors (Hirose DF12(3.0)-80DS-0.5V)
- >  $1 \times FMC$  connector (ASP-134602-01)



#### re-optimised PACIFIC Carrier Board r4

### **Redesign of PACIFIC Carrier Board**

#### We decided to re-optimize the routing of the PACIFIC Carrier Board

- for a higher production yield
- more strict routing constrains, to gain some margin for the sampling window size
- → 4 pairs of PACIFIC Clock lines (CLKIN\_0~3) : routing length match < 1mm
- → 4 SYNC lines (SYNC\_0~3): routing length match < 1 mm
- → 64 pairs of data lines (DATA\_0~3\_X) : routing length match <3mm.
- ➢ well seperate the analog input signals and the output data lines, the CLOCK lines
- from 8-layers to 14-layers
- Calculate impedance for Halogen Free (TU-862HF), and keep thickness 1.7mm



For the first 250 PACIFIC Carrier Boards, we will assemble first 10 PCBs, check with the SciFi full electronics (MB+CB) to make sure everything works fine after this optimization.



re-optimised PACIFIC Carrier Board r4

21

### **Redesign of PACIFIC Carrier Board**



#### **Redesign of PACIFIC Carrier Board & Mass Production**





2018.09 - First 250 PACIFIC Carrier Boards finished ! (for first C-Frame of SciFi)

### First Setup of SciFi C-Frame



#### Test with SiPM + Light Injection System



First Setup of SciFi C-Frame (Sci-Fi milestone of 2018)

### **BER test with SciFi FE**







### QA System for PACIFIC chips

Custom designed test DAQ (PACIFICROB): [fully tested, 4 for Heidelberg, 3 for Barcelona, 3 for Valencia]

- ✓ Altera Cyclone FPGA (clock generation, ASIC configuration, data process, sensor readout ...)
- ✓ precision clock conditioner to fine tune the clock for each ASIC Power adapter board
- ✓ (LVDS-SLVS convertor)
- ✓ 8-channel, 12-bit ADC
- ✓ USB interface to PC
- Socket Board:
  - ✓ 4 sockets to nip chips
  - ✓ Connected with FMC & controlling cable
- DC power supply
  - ✓ Output 5V/3A at least
- Linux PC
- Robot arm (Barcelona)



Mid connector





### Main features of test results for one chip





test automatically update result to DB



finish all 1<sup>st</sup> batch 1420 PACIFIC5q test



final check the QA test routine

LHCb Production Interface



QA test running : 10 ASICs/run, ~100ASICs/hour

Xiaoxue Han (Logout)

#### All results can be found in Sci-Fi Production DB

_ R	eadout Box Productions	Find by Bar	code			Search	ł	nttps	://	scifi.	phy	/si.u	uni-ł	neidell	be	rg.c	le/d	b/prod/	Н	Jover prev
	PACIFIC ASICs										New PAC	CIFIC ASI	C (total: 141	0 <u>CSV</u> , <u>SCSV</u> )						
	PACIFIC Boards	Show filler																		
<b>_</b> Q	Readout Box Operations uaroses QuarosSystems	Inventory	Origin	ID	Arrived	Tested	Location	Dimensions [mm x mm x mm]	Weight [kg]	<u>Material</u> composition	Comment	Initial current [mA]	Configured current [mA]	Failure	Vref	VrefDCFB	Summary report [.pdf]	Raw data [.root]	PACIFIC Boards	
	SiPMs for Quaroses Adapter boards	EPA00009	PI	PACIFIC5_Q- Adummy	2018-05-26	2018-06-07						0	0	I2C fails	0	0	-	rawData AsicQA testsystem8 ASICID PACIFIC5 Q- Adummy.root 2018-06-07 19:48:46 by Xiaoxue Han	Q	Modify
	Spiroc FEs Power supply units USBboards Laser mezzanines Spiroc ASICs Upload Quaros fileses	EPA00010		PACIFIC5_Q- A2104	2018-05-26	2018-06-07						434.4	511.8	trimDAC fails	27	6	PACIFIC5 Q- A2104.pdf 2018-06-07 20:21:10 by Xiaoxue Han	rawData AsicOA testsystem8 ASICID PACIFIC5 O- A2104 root 2616/06/07 19:48:50 by Xiaosue Han	<u>0</u>	Modify
		EPA00011	Ы	PACIFIC5_Q- A2105	2018-05-26	2018-06-07						411	511.8	Working	25	9	PACIFIC5 Q- A2105.pdf 2018-08-07 19:48:55 by Xisoxue Han	rawData AsiCOA teatsystem8 ASICID PACIFIC5 Q- A2105:rod 2018-06-07 19 48:58 by Xiaoxue Han	Q	<u>Modify</u>
		EPA00012	PI	PACIFIC5_Q- A2106	2018-05-26	2018-06-07						458.8	515	Working	29	9	PACIFIC5 Q- A2106.pdf 2018.06.07 19:49:02 by Xisoxue Han	rawData AsiCOA testsystem® ASICID PACIFIC5 Q- A2108.rod 2318-06-07 19 49 05 by Xiaoxue Han	٥	Modify

### QA test for 1<sup>st</sup> batch of packaged PACIFIC5q



### QA System for Carrier Boards

Custom designed test DAQ (PACIFICROB): [fully tested, 3 for Heidelberg (delivered), 3 for Barcelona, 3 for Valencia]

- ✓ Altera Cyclone FPGA (clock generation, ASIC configuration, data process, sensor readout ...)
- ✓ precise clock conditioner to fine tune the clock for each ASIC
- ✓ LVDS-SLVS convertor
- ✓ 8-channel, 12-bit ADC
- ✓ USB interface to PC

FMC connector intermedia board:

- ✓ Simple pin-to-pin adapter PCBs
- ✓ To avoid broken FMC connectors
- Charge injection board
- DC power supply
  - ✓ Output 5V/3A at least

Arbitrary waveform generatorLinux PC





### QA System for Carrier Boards

Custom designed test DAQ (PACIFICROB): [fully tested, 3 for Heidelberg (delivered), 3 for Barcelona, 3 for Valencia]

- ✓ Altera Cyclone FPGA (clock generation, ASIC configuration, data process, sensor readout ...)
- precision clock conditioner to fine tune the clock for each ASIC
   (1) DS\_SIVS convertor)
   External charge injection board
- ✓ (LVDS-SLVS convertor)
- ✓ 8-channel, 12-bit ADC
- ✓ USB interface to PC
- FMC connector intermedia board:
  - ✓ Simple pin-to-pin adapter PCBs
  - ✓ To avoid broken FMC connectors
- Charge injection board

#### DC power supply

- ✓ Output 5V/3A at least
- Arbitrary waveform generator
- Linux PC



FMC adapter board Mid connector



Controlling cable

Voltage sensor

External trigger



### First 250 PACIFIC Carrier Boards Tested



### LHCb Upgrade I: SciFi

- 一名博士后和一名博士生分别在CERN和海德堡参加SciFi 探测器的工作
- > 作为主力完成了全部闪烁光纤的质量检测 (QA)
- > 负责把SciFi探测器几何描述数据库从XML 转换为DD4HEP
- > 开发SciFi 探测器监控软件





### LHCb Upgrade I: SciFi (LHCb China Group)



LHCb China Group (2018) finished:

- ✓ >1500 PACIFIC ASICs tested
- $\checkmark$  Frontend Boards redesigned and verified
- ✓ 250 Frontend Boards manufactured and tested in China
- ✓ 6 Readout Electronic Quality Assurance System set up in Heidelberg, Barcelona and Valencia



#### **\*** 2019 To Do:

- ✓ ALL 12,000 PACIFIC ASICs to test (with Barcelona group)
- ✓ ALL 2,500 Frontend Boards to manufacture in China [in progress] and to test (with Valencia group)

### LHCb Upgrade I: SciFi

#### **Production Schedule**





# LHCb Upgrade I: UT

### LHCb Upgrade I: Upstream Tracker (UT)

- 在高辐射的中心区域使用更抗辐射的n-in-p的硅微条技术,而在其余部分使用技术相对成熟价格较低的p-in-n探测器.
- 前端读出芯片(SALT)采集信号,数字化,并压缩数据,然后将电子信号传送到UT板条顶端的数据控制板 (DCB); DCB收集数据,转化为光信号,输送到地表的数据收集系统.



LHCb Upgrade I: Upstream Tracker (UT)
□ 在UT研发和建造过程中发挥关键作用,协调电子学及读出系统各部件的发展。
□ 测试 SALT芯片(版本2)的性能,及纠正设计问题。
□ 在10月份参加并成功领导了读出系统的第一次束流测试。





## LHCb Upgrade II: ECAL

### LHCb Upgrade II: 电磁量能器升级的模拟研究

- 利用Delphes软件开展快速模拟,优化电磁量能器的设计
  - > 通过对簇射横向发展的模拟,研究光子能量分辨和π⁰质量分辨



- 通过计算机模拟,研究电磁量能器的背景粒子流
  - > Upgrade II 本底增加,理解本底的大小、能量流分布对电磁量器 的设计和性能优化至关重要

结论:现有量能器不能满足Upgrade II 要求,需要提高颗粒度,引入时间信息。 下一步研究:高颗粒度取样型量能器 + 硅探测层用于提供快速时间测量

## Thank you!

Questions?



第四届中国LHC物理工作会议

References:

.

.

- https://cds.cern.ch/record/2630472/files/passalevaichep%2007.07.pdf
- <u>https://cds.cern.ch/record/2650584/files/181206\_Kruger.pdf</u>
- <u>https://cds.cern.ch/record/2648754/files/grauges-LHCb-</u> <u>NagoyaHfNPFP.pdf</u>



. . . . . .